



AF/2800
Reply under 37 CFR 1.116
--Expedited Procedure--
Technology Center 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yamaguchi, et al.

Serial No.: 10/087,556

Filed: 03/01/02

For: Semiconductor Device and Bump Formation Method

Docket No.: 1131471
Examiner: Im, Junghwa M.
Art Unit: 2811

#8/Response (1/6)
5/22/03
Shu th

Amendment under 37 CFR 1.116

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

May 13, 2003.

Elizabeth Austin
Elizabeth Austin

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 03/13/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

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